

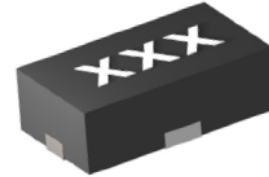
Features

- Supports up to 50 W Power
- Low Insertion Loss: 0.1 dB up to 2.5 GHz
- High Isolation: 16 dB @ 1 GHz
- RoHS* Compliant

Description

A broadband medium power switch element in a 2.6 x 1.5 mm DFN package. This device is Electrical Series with Thermal to Ground (EST2G). This device is designed for wireless infrastructure applications and test instruments.

It is well suited for other applications from 45 MHz up to 2.5 GHz



2615
(Plastic Molded DFN)

Electrical Specifications: $T_C = +25^\circ\text{C}$ (unless otherwise specified)

Parameter	Test Conditions	Units	Min.	Typ.	Max.
Breakdown Voltage (V_{BR})	$I_R = 10 \mu\text{A}$	V	500	—	—
Lifetime (t)	$I_F = 10 \text{ mA}$, $I_R = 6 \text{ mA}$, 10%/90%	ns	—	1200	—
I-Region (w)	I-Layer	μm	—	40	—
Series Resistance (R_S)	$I_F = 100 \text{ mA}$	Ω	—	0.4	0.6
Junction Capacitance (C_J)	$V_R = 50 \text{ V}$, 1 MHz	pF	—	0.18	0.25
Insertion Loss (I_L)	$I_F = 100 \text{ mA}$, 2.5 GHz	dB	—	0.15	0.30
Input Return Loss (IR_L)	$I_F = 100 \text{ mA}$, 2.5 GHz	dB	20	24	—
Isolation (I_{SO})	$V_R = -10 \text{ V}$, 1.0 GHz $V_R = -10 \text{ V}$, <2.0 GHz	dB	14 9	16 11	—

* Restrictions on Hazardous Substances, European Union Directive 2011/65/EU.

Absolute Maximum Ratings^{1,2}

Parameter	Absolute Maximum
Breakdown Voltage (V_R)	500 V
Forward Current (I_{FDC})	200 mA
Theta (θ_{JC})	12°C/W
Junction Temperature (T_J)	175°C
Storage Temperature (T_{STG})	-65°C to +250°C
Mounting Temperature (T_{MTG})	+260°C per JEDEC STD-J-20C

1. Exceeding any one or combination of these limits may cause permanent damage to this device.
2. MACOM does not recommend sustained operation near these survivability limits.

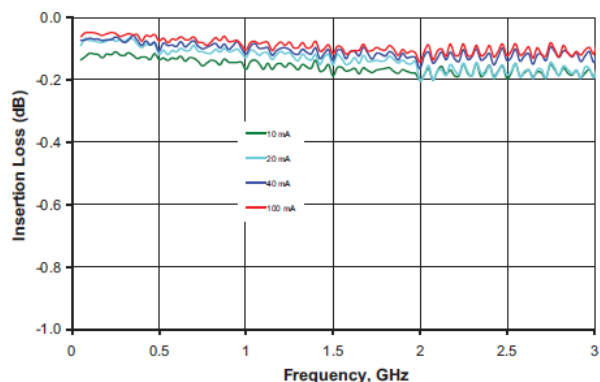
Handling Procedures

Please observe the following precautions to avoid damage:

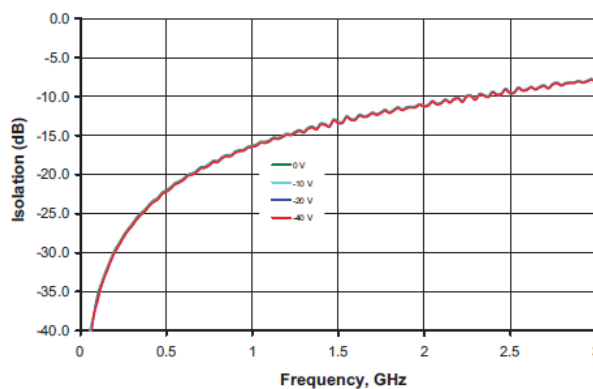
Static Sensitivity

These electronic devices are sensitive to electrostatic discharge (ESD) and can be damaged by static electricity. Proper ESD control techniques should be used when handling these Class 0 (HBM) devices.

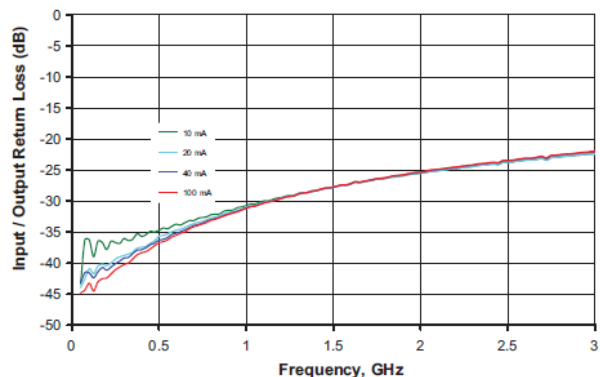
Insertion Loss



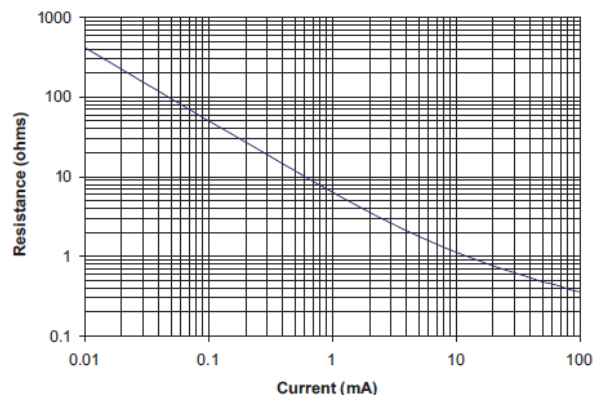
Isolation



Input / Output Return Loss



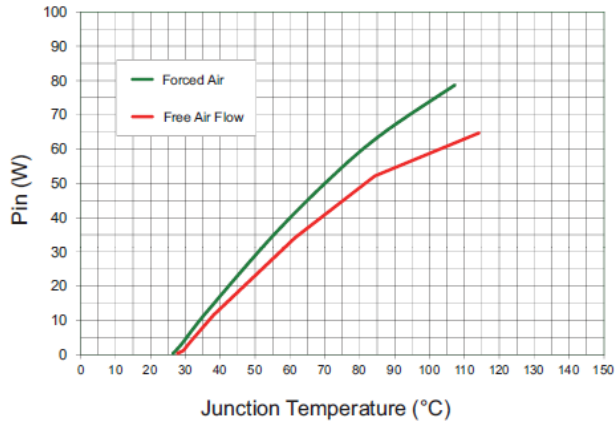
Series Resistance vs. Current, 500 MHz



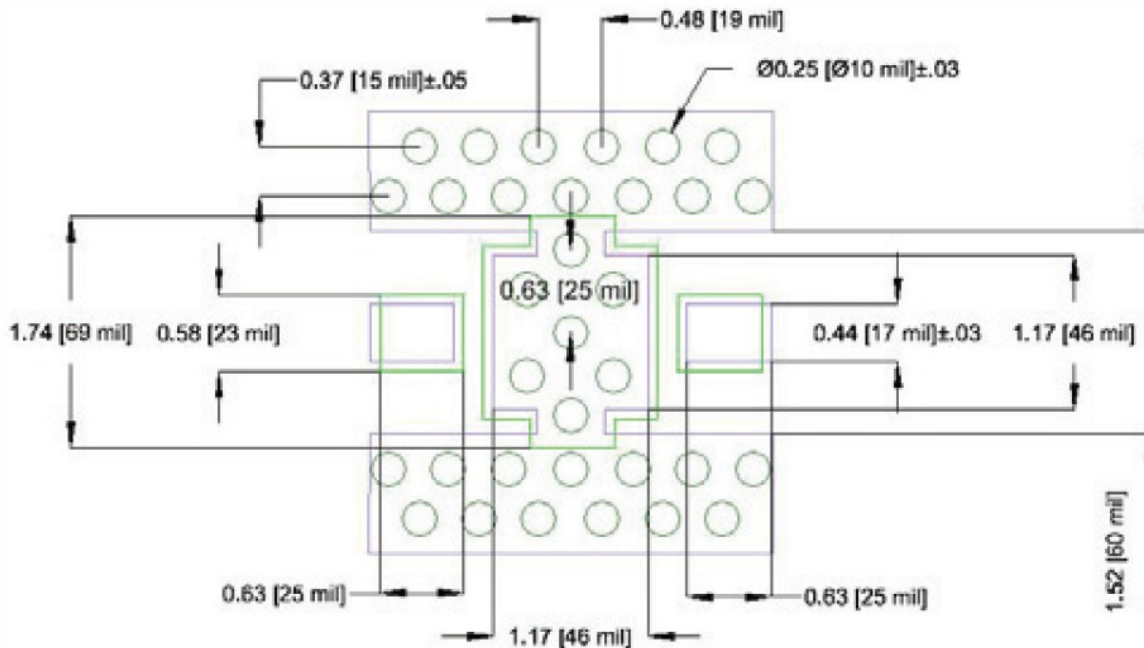
Pin Diode Switch Element

Rev. V1

Junction Temperature vs. P_{IN}
(Mounted on Heat Sink @ +25°C, 1.3 GHz)



Printed Circuit Board Layout



Unless otherwise specified:

1. Tolerance ± 0.10 mm
2. Soldermask to extend 3 mils beyond metal trace
3. Vias under package filled with copper or soldermask
4. Use circles or squares for thermal land stencil such that there is only 50 to 80% solder paste coverage

Outline

